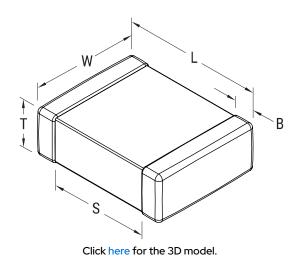


C1812C271JHGACTU

Specifications

Insulation Resistance

Aliases (C1812C271JHGAC7800) SMD Comm COG HV, Ceramic, 270 pF, 5%, 3,000 VDC, COG, SMD, MLCC, Ultra-Stable, Low Loss, Class I, 1812



General Information	
Series	SMD Comm COG HV
Style	SMD Chip
Description	SMD, MLCC, Ultra-Stable, Low Loss, Class I
Features	Ultra-Stable, Low Loss, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	87 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1812
L	4.5mm +/-0.3mm
W	3.2mm +/-0.3mm
Т	2mm +/-0.20mm
S	2.3mm MIN
В	0.6mm +/-0.35mm

Capacitance	270 pF
Measurement Condition	1 MHz 1.0Vrms
Capacitance Tolerance	5%
Voltage DC	3000 VDC
Dielectric Withstanding Voltage	3,600 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour

100 GOhms

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	500

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